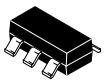
PACDN042

Transient Voltage Suppressors and ESD Protectors

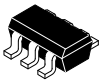
ON Semiconductor®

http://onsemi.com

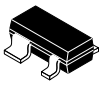
SOT23−3
CASE 318



SOT23−5
CASE 527AH

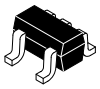


SOT23−6
CASE 527AJ



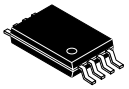
SOT−143
CASE 527AF

SC70−3
CASE 419AB



CS70−5
CASE 419AC

SC70−6
CASE 419AD



TSSOP8
CASE 948AL

MSOP8
CASE 846AB

Product Description

The PACDN042/43/44/45/46 family of transient voltage suppressor arrays provide a very high level of protection for sensitive electronic components that may be subjected to electrostatic discharge (ESD). The PACDN042/43/44/45/46 devices safely dissipate ESD strikes, exceeding the IEC 61000−4−2 International Standard, Level 4 (±8 kV contact discharge). All pins are rated to withstand ±20 kV ESD pulses using the IEC 61000−4−2 contact discharge method. Using the MIL−STD−883D (Method 3015) specification for Human Body Model (HBM) ESD, all pins are protected from contact discharges of greater than ±30 kV.

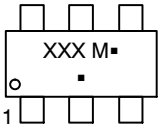
Features

- Two, Three, Four, Five, or Six Transient Voltage Suppressors
- Compact SMT Package Saves Board Space and Facilitates Layout in Space−Critical Applications
- In−System ESD Protection to ±20 kV Contact Discharge, per the IEC 61000−4−2 International Standard
- These Devices are Pb−Free and are RoHS Compliant

Applications

- ESD Protection of PC Ports, Including USB Ports, Serial Ports, Parallel Ports, IEEE1394 Ports, Docking Ports, Proprietary Ports, etc.
- Protection of Interface Ports or IC Pins which are Exposed to High ESD Levels

MARKING DIAGRAM

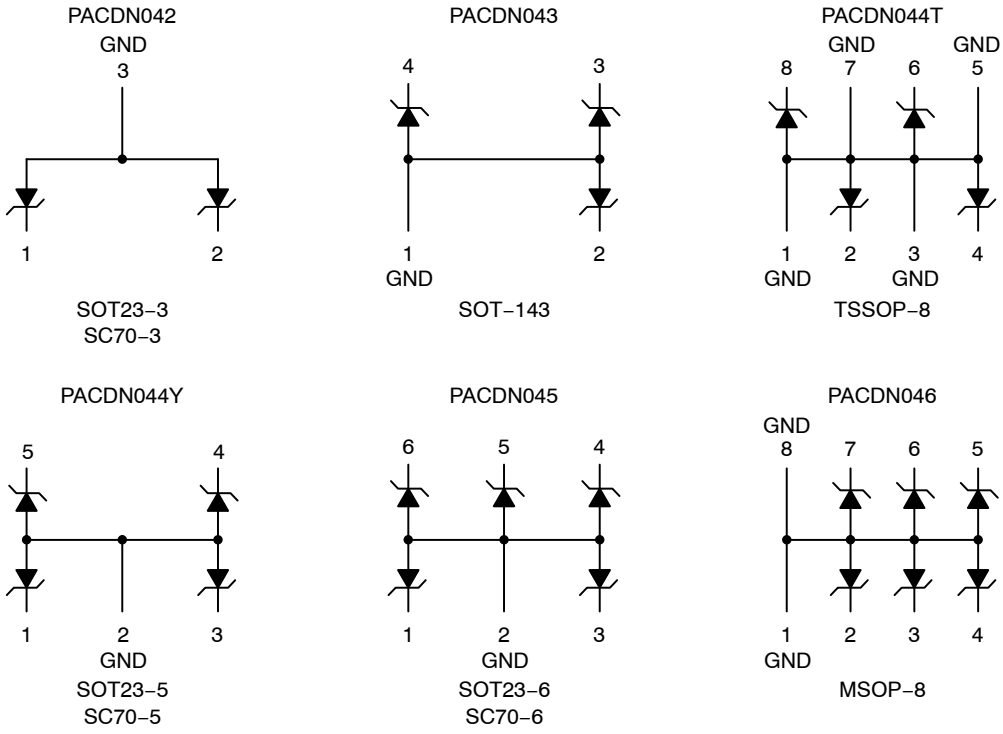


XXX = Specific Device Code
M = Date Code
▪ = Pb−Free Package
(Note: Microdot may be in either location)

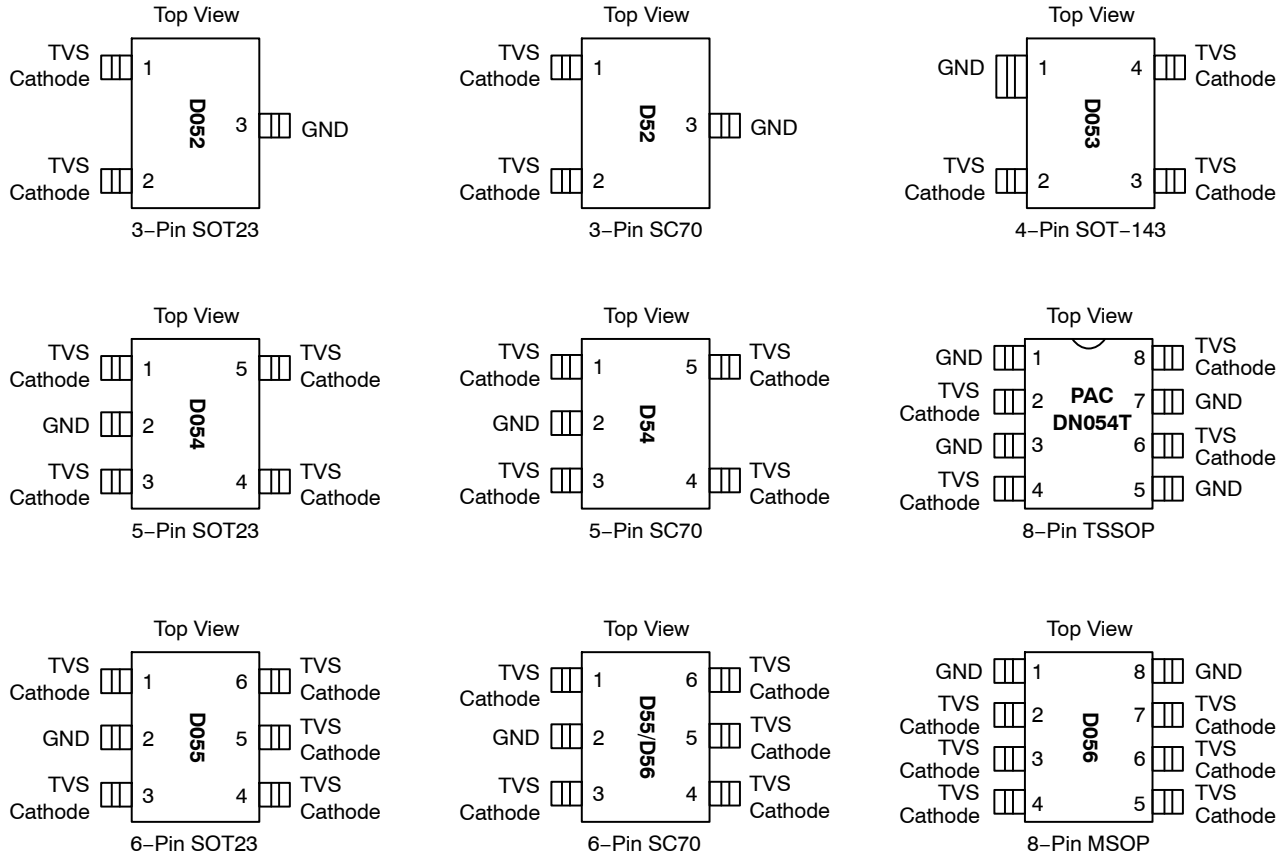
ORDERING INFORMATION

(see the last page of this document)

ELECTRICAL SCHEMATIC



PACKAGE / PINOUT DIAGRAMS



Note: SOT23, SC70, SOT−143, TSSOP, and MSOP Packages may differ in size. These drawings are not to scale.

Table 1. PIN DESCRIPTIONS

Pins	Name	Description
(Refer to Package Outline Drawings)	TVS Cathode	The cathode of the respective TVS diode, which should be connected to the node requiring transient voltage protection.
(Refer to Package Outline Drawings)	GND	The anode of the TVS diodes.

SPECIFICATIONS

Table 2. ABSOLUTE MAXIMUM RATINGS

Parameter	Rating	Units
Storage Temperature Range	−65 to +150	°C
Package Power Dissipation SC70 SOT23−3, SOT23−5, SOT23−6, SOT−143 TSSOP, MSOP	 0.2 0.225 0.5	W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 3. STANDARD OPERATING CONDITIONS

Parameter	Rating	Units
Operating Temperature	−40 to +85	°C

Table 4. ELECTRICAL OPERATING CHARACTERISTICS

Symbol	Parameter	Conditions	Min	Typ	Max	Units
C	Capacitance	T_A = 25°C, 2.5 VDC, 1 MHz		30		pF
V_{RSO}	Reverse Stand−off Voltage	I_R = 10 μA, T_A = 25°C	5.5			V
		I_R = 1 mA, T_A = 25°C	6.1			V
I_{LEAK}	Leakage Current	V_{IN} = 5.0 VDC, T_A = 25°C		1	100	nA
V_{SIG}	Small Signal Clamp Voltage Positive Clamp Negative Clamp	 I = 10 mA, T_A = 25°C I = −10 mA, T_A = 25°C	 6.2 −0.4	 6.8 −0.8	 8 −1.2	V
V_{ESD}	ESD Withstand Voltage Human Body Model, MIL−STD−883, Method 3015 Contact Discharge per IEC 61000−4−2 Standard	 (Note 1) (Note 1)	 ±30 ±20			kV
R_D	Diode Dynamic Resistance Forward Conduction Reverse Conduction			 1.0 1.4		Ω

1. ESD voltage applied between channel pins & ground, one pin at a time; all other channel pins open; all GND pins grounded.

PERFORMANCE INFORMATION

Diode Capacitance

Typical diode capacitance with respect to positive TVS cathode voltage (reverse voltage across the diode) is given in Diode Capacitance vs. Reverse Voltage.

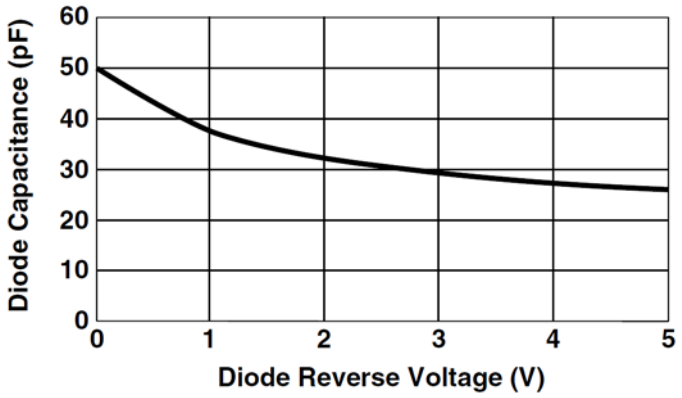


Figure 1. Diode Capacitance vs. Reverse Voltage

Typical High Current Diode Characteristics

Measurements are made in pulse mode with a nominal pulse width of 0.7 mS.

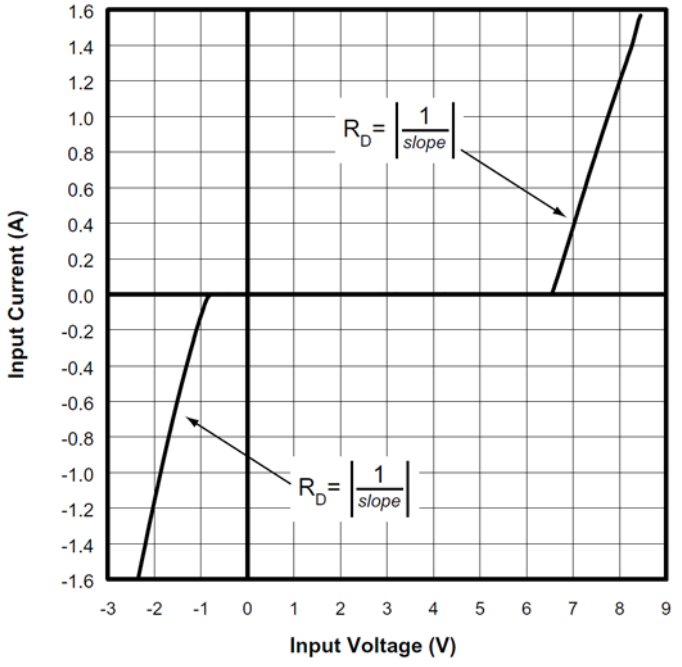
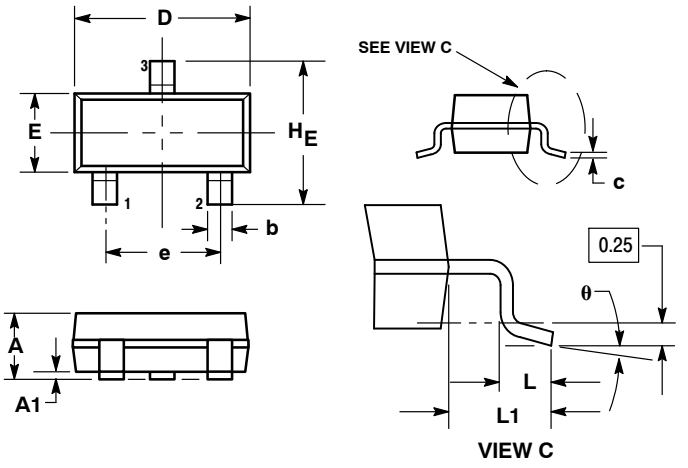


Figure 2. Typical Input VI Characteristics
(Pulse−mode measurements, pulse width = 0.7 mS nominal)

PACKAGE DIMENSIONS

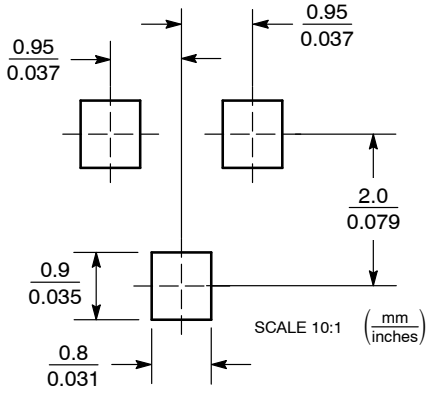
SOT−23 (TO−236)
CASE 318−08
ISSUE AP



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: INCH.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

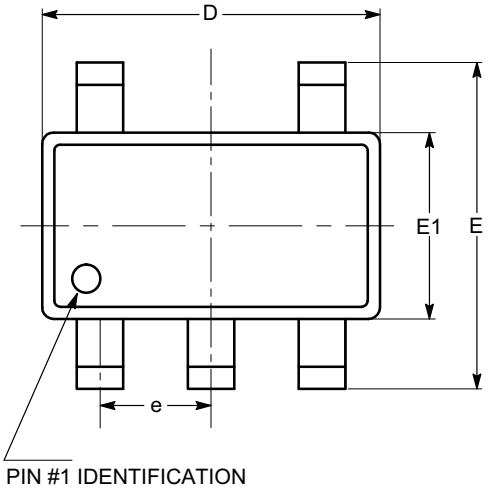
	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1.00	1.11	0.035	0.040	0.044
A1	0.01	0.06	0.10	0.001	0.002	0.004
b	0.37	0.44	0.50	0.015	0.018	0.020
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
e	1.78	1.90	2.04	0.070	0.075	0.081
L	0.10	0.20	0.30	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
H_E	2.10	2.40	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°

SOLDERING FOOTPRINT



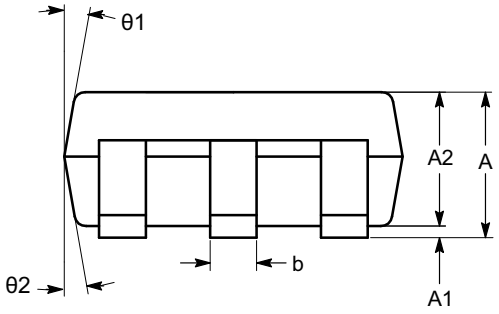
PACKAGE DIMENSIONS

SOT−23, 5 Lead
CASE 527AH−01
ISSUE O

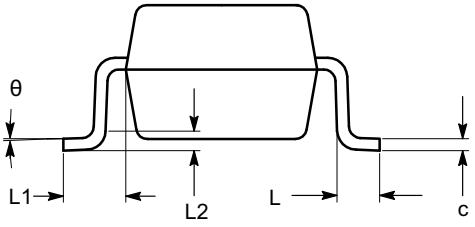


TOP VIEW

SYMBOL	MIN	NOM	MAX
A	0.90		1.45
A1	0.00		0.15
A2	0.90	1.15	1.30
b	0.30		0.50
c	0.08		0.22
D		2.90 BSC	
E		2.80 BSC	
E1		1.60 BSC	
e		0.95 BSC	
L	0.30	0.45	0.60
L1		0.60 REF	
L2		0.25 REF	
θ	0°	4°	8°
θ1	5°	10°	15°
θ2	5°	10°	15°



SIDE VIEW

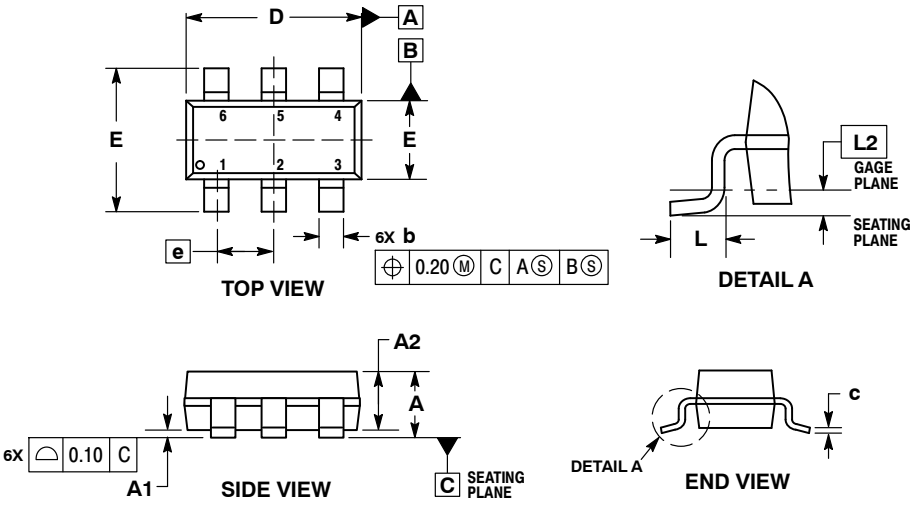


END VIEW

Notes:
(1) All dimensions in millimeters. Angles in degrees.
(2) Complies with JEDEC standard MO-178.

PACKAGE DIMENSIONS

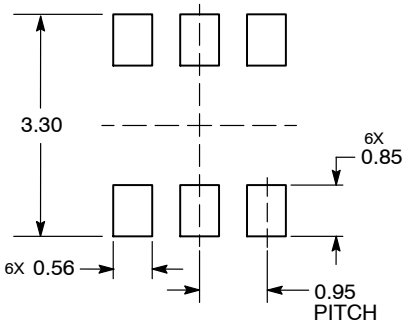
SOT−23, 6 Lead
CASE 527AJ−01
ISSUE A



NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DATUM C IS THE SEATING PLANE.

	MILLIMETERS	
DIM	MIN	MAX
A	---	1.45
A1	0.00	0.15
A2	0.90	1.30
b	0.20	0.50
c	0.08	0.26
D	2.70	3.00
E	2.50	3.10
E1	1.30	1.80
e	0.95 BSC	
L	0.20	0.60
L2	0.25 BSC	

RECOMMENDED SOLDERING FOOTPRINT*

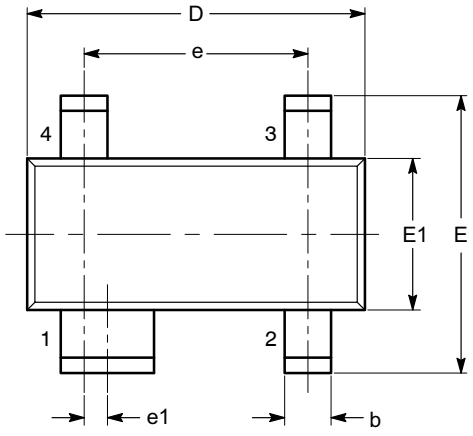


DIMENSIONS: MILLIMETERS

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

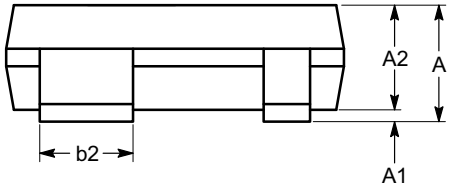
PACKAGE DIMENSIONS

SOT−143, 4 Lead
CASE 527AF−01
ISSUE A

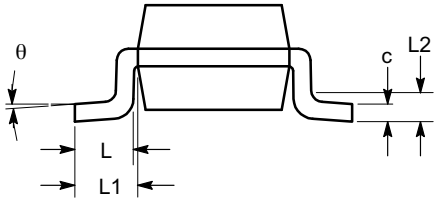


TOP VIEW

SYMBOL	MIN	NOM	MAX
A	0.80		1.22
A1	0.05		0.15
A2	0.75	0.90	1.07
b	0.30		0.50
b2	0.76		0.89
c	0.08		0.20
D	2.80	2.90	3.04
E	2.10		2.64
E1	1.20	1.30	1.40
e	1.92 BSC		
e1	0.20 BSC		
L	0.40	0.50	0.60
L1	0.54 REF		
L2		0.25	
θ	0°		8°



SIDE VIEW

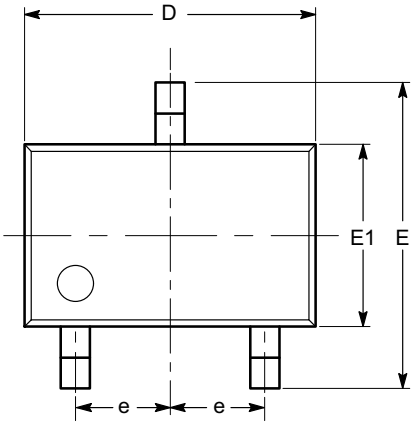


END VIEW

Notes:
(1) All dimensions are in millimeters. Angles in degrees.
(2) Complies with JEDEC TO-253.

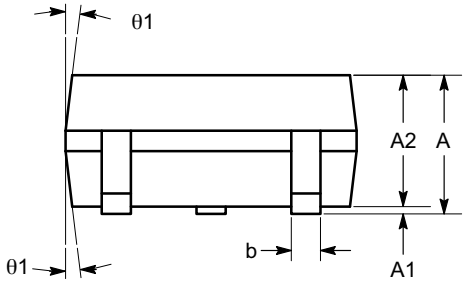
PACKAGE DIMENSIONS

SC−70, 3 Lead, 1.25x2
CASE 419AB−01
ISSUE O

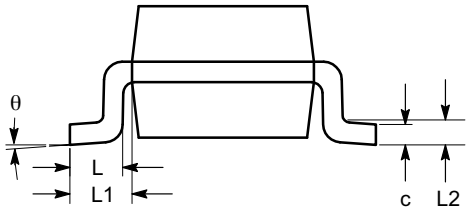


TOP VIEW

SYMBOL	MIN	NOM	MAX
A	0.80		1.10
A1	0.00		0.10
A2	0.80	0.90	1.00
b	0.15		0.30
c	0.08		0.22
D	1.80	2.00	2.20
E	1.80	2.10	2.40
E1	1.15	1.25	1.35
e		0.65 BSC	
L	0.26	0.36	0.46
L1		0.42 REF	
L2		0.15 BSC	
θ	0°		8°
θ1	4°		10°



SIDE VIEW

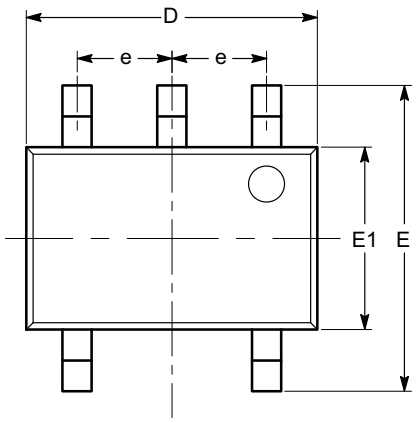


END VIEW

Notes:
(1) All dimensions are in millimeters. Angles in degrees.
(2) Complies with JEDEC MO-203.

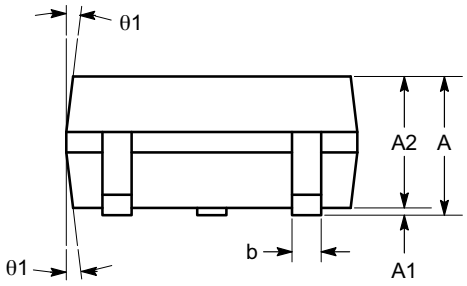
PACKAGE DIMENSIONS

SC−88A (SC−70 5 Lead), 1.25x2
CASE 419AC−01
ISSUE A

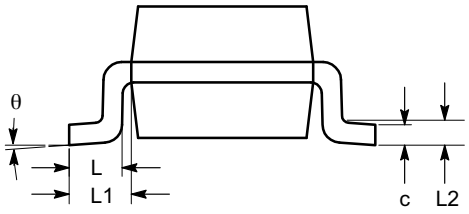


TOP VIEW

SYMBOL	MIN	NOM	MAX
A	0.80		1.10
A1	0.00		0.10
A2	0.80		1.00
b	0.15		0.30
c	0.10		0.18
D	1.80	2.00	2.20
E	1.80	2.10	2.40
E1	1.15	1.25	1.35
e		0.65 BSC	
L	0.26	0.36	0.46
L1		0.42 REF	
L2		0.15 BSC	
θ	0°		8°
θ1	4°		10°



SIDE VIEW

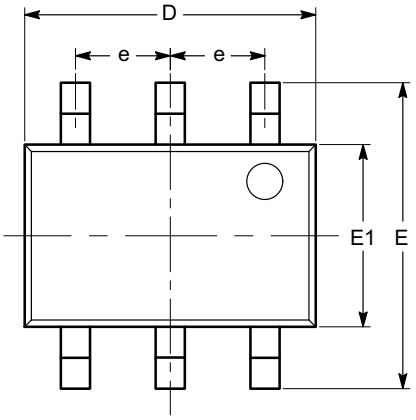


END VIEW

Notes:
(1) All dimensions are in millimeters. Angles in degrees.
(2) Complies with JEDEC MO-203.

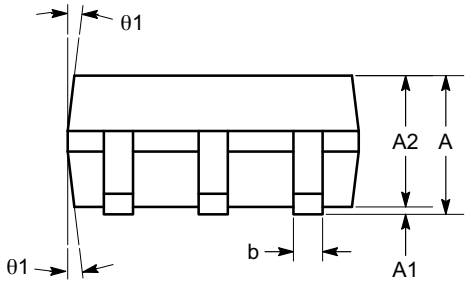
PACKAGE DIMENSIONS

SC−88 (SC−70 6 Lead), 1.25x2
CASE 419AD−01
ISSUE A

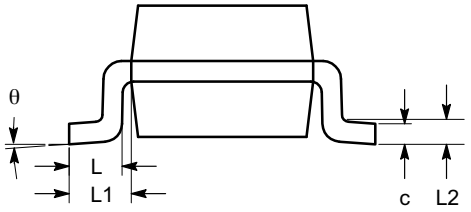


TOP VIEW

SYMBOL	MIN	NOM	MAX
A	0.80		1.10
A1	0.00		0.10
A2	0.80		1.00
b	0.15		0.30
c	0.10		0.18
D	1.80	2.00	2.20
E	1.80	2.10	2.40
E1	1.15	1.25	1.35
e		0.65 BSC	
L	0.26	0.36	0.46
L1		0.42 REF	
L2		0.15 BSC	
θ	0°		8°
θ1	4°		10°



SIDE VIEW



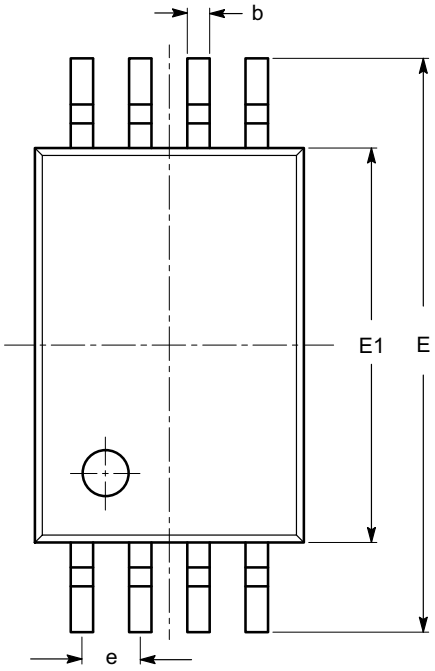
END VIEW

Notes:
(1) All dimensions are in millimeters. Angles in degrees.
(2) Complies with JEDEC MO-203.

PACKAGE DIMENSIONS

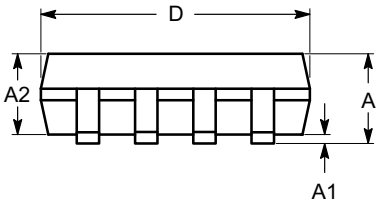
TSSOP8, 4.4x3
CASE 948AL−01
ISSUE O

DATE 19 DEC 2008

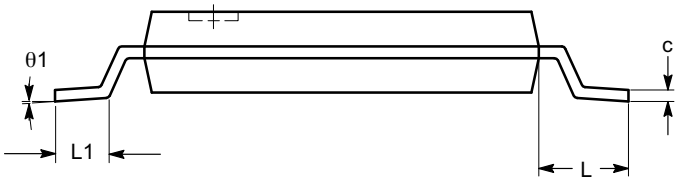


TOP VIEW

SYMBOL	MIN	NOM	MAX
A			1.20
A1	0.05		0.15
A2	0.80	0.90	1.05
b	0.19		0.30
c	0.09		0.20
D	2.90	3.00	3.10
E	6.30	6.40	6.50
E1	4.30	4.40	4.50
e	0.65 BSC		
L	1.00 REF		
L1	0.50	0.60	0.75
θ	0°		8°



SIDE VIEW

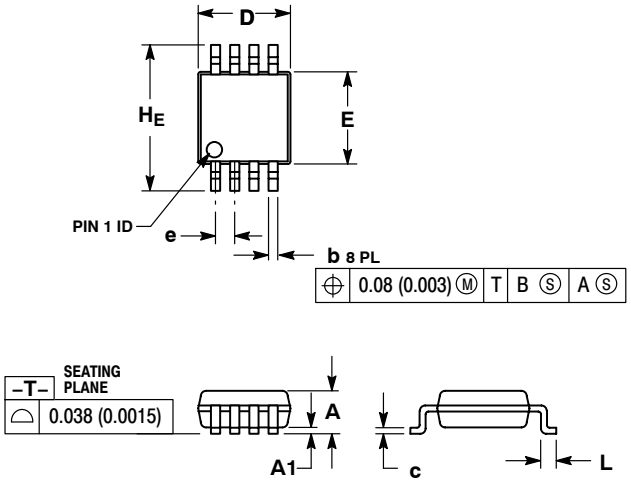


END VIEW

Notes:
(1) All dimensions are in millimeters. Angles in degrees.
(2) Complies with JEDEC MO-153.

PACKAGE DIMENSIONS

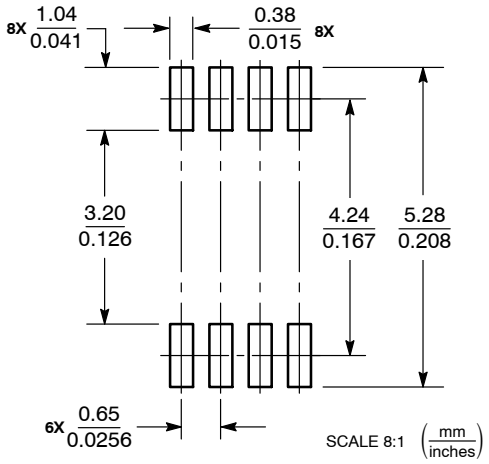
MSOP8
CASE 846AB−01
ISSUE O



NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH, PROTRUSIONS OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.
5. 846A−01 OBSOLETE, NEW STANDARD 846A−02.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
A	−−	−−	1.10	−−	−−	0.043
A1	0.05	0.08	0.15	0.002	0.003	0.006
b	0.25	0.33	0.40	0.010	0.013	0.016
c	0.13	0.18	0.23	0.005	0.007	0.009
D	2.90	3.00	3.10	0.114	0.118	0.122
E	2.90	3.00	3.10	0.114	0.118	0.122
e	0.65 BSC			0.026 BSC		
L	0.40	0.55	0.70	0.016	0.021	0.028
H_E	4.75	4.90	5.05	0.187	0.193	0.199

SOLDERING FOOTPRINT*



*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ORDERING INFORMATION

Device	Package	Shipping
PACDN042Y3R	SOT23−3 (Pb−Free)	3000/Tape & Reel
PACDN044Y5R	SOT23−5 (Pb−Free)	3000/Tape & Reel
PACDN045Y6R	SOT23−6 (Pb−Free)	3000/Tape & Reel
PACDN043Y4R	SOT−143 (Pb−Free)	3000/Tape & Reel
PACDN042YB3R	SC70−3 (Pb−Free)	3000/Tape & Reel

ORDERING INFORMATION (cont'd)

Device	Package	Shipping
PACDN044YB5R	SC70−5 (Pb−Free)	3000/Tape & Reel
PACDN045YB6R	SC70−6 (Pb−Free)	3000/Tape & Reel
PACDN045YB6R−R	SC70−6 (Pb−Free)	3000/Tape & Reel
PACDN044TR	TSSOP8 (Pb−Free)	2500/Tape & Reel
PACDN046MR	MSOP8 (Pb−Free)	4000/Tape & Reel

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